CINOS CLEANING TECHNOLOGY

Chemical Assisted Ultra Sonic

CAUS™

CAUS™ is the dedicated cleaning device for cleaning particles inside of fine holes. The cleaning chemical cannot smoothly penetrate the holes of the semiconductor manufacturing equipment due to the surface tension of the cleaning chemical and the substrate and, others. Therefore, it is impossible to completely remove particles with general immersion cleaning, and a lot of particles are generated when the chamber is installed. **CAUS™ is the technology where ultrasonic waves are applied to improve the activation and injection of cleaning chemicals with improved surface energy and to generate cavitation of the chemical. With this technology, the process by-products and particles inside of the holes can be effectively removed.**

Point

- Cavitation
- Minimize Variation
- Reactivity

CINOS

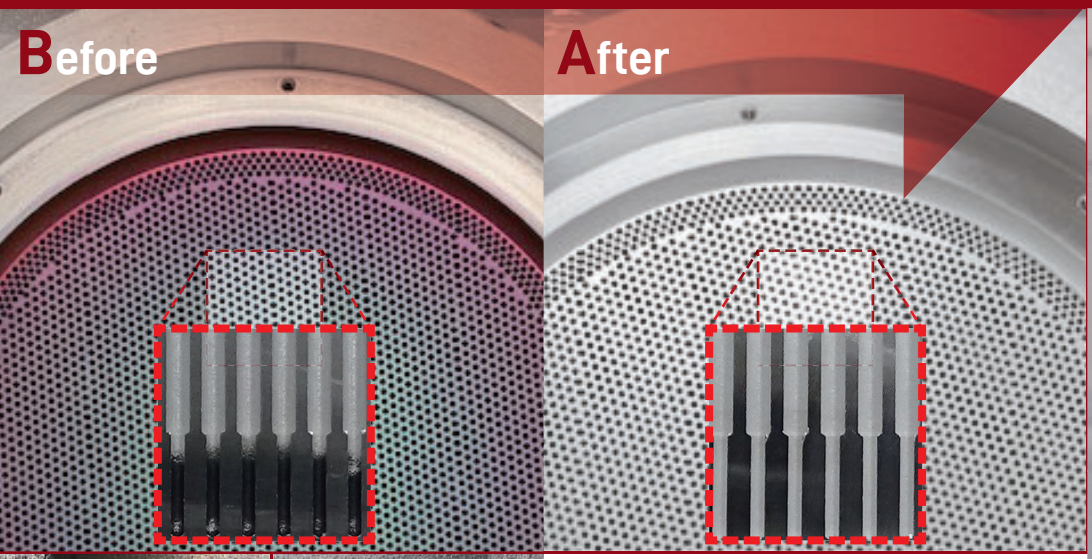
Before/After
CAUS™

13 μm Increase

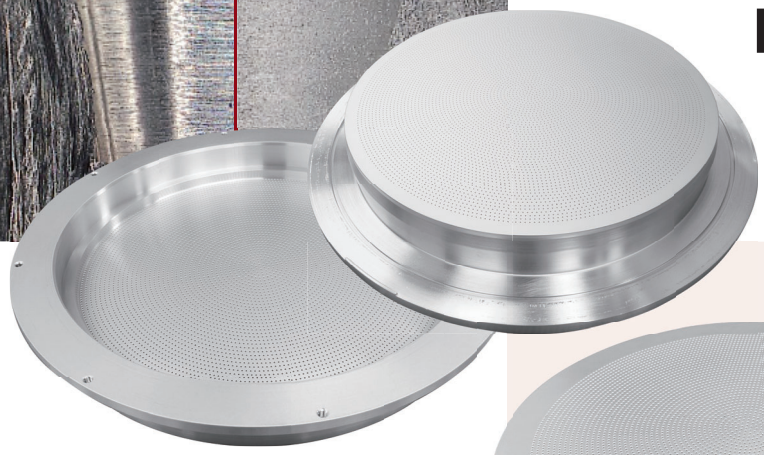
Minimized Change

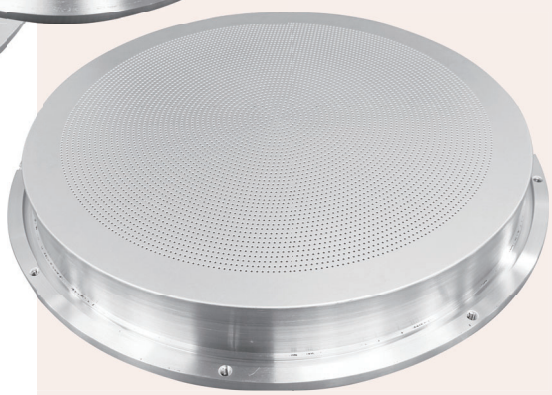
Cleaning Liquid + **Ultrasonic wave**

The Ultrasonic waves that cause cavitation of cleaning chemicals can remove the deposition inside of the holes effectively.



Best Solution For Hole Type





CAUS™ can clean any parts with holes.

CINOS CAUS™ Driving Appearance

CINOS

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